

SOLDER ALLOY, SOLDER BALL, SOLDER PREFORM, SOLDER PASTE, AND SOLDER JOINT

ABSTRACT

Provided are a solder alloy, a solder ball, a solder preform, a solder paste, and a solder joint which have excellent wettability and high reliability by prevention of rupture of solder joints. The solder alloy has an alloy composition consisting of, by mass%, Ag: 1.0 to 3.8%, Cu: 0.4 to 0.8%, Sb: 0.03 to 2.90%, In: 1.1 to 4.2%, Ni: 0.01 to 0.14%, Bi: 0.1 to 5.0%, with the balance being Sn.

[Figure 1a]